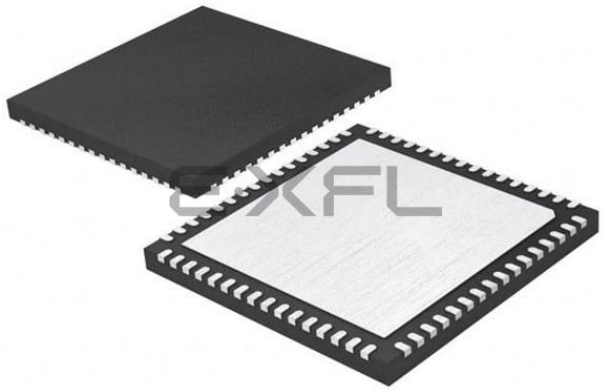
Microchip Technology - DSPIC33EP128GP506T-E/MR Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

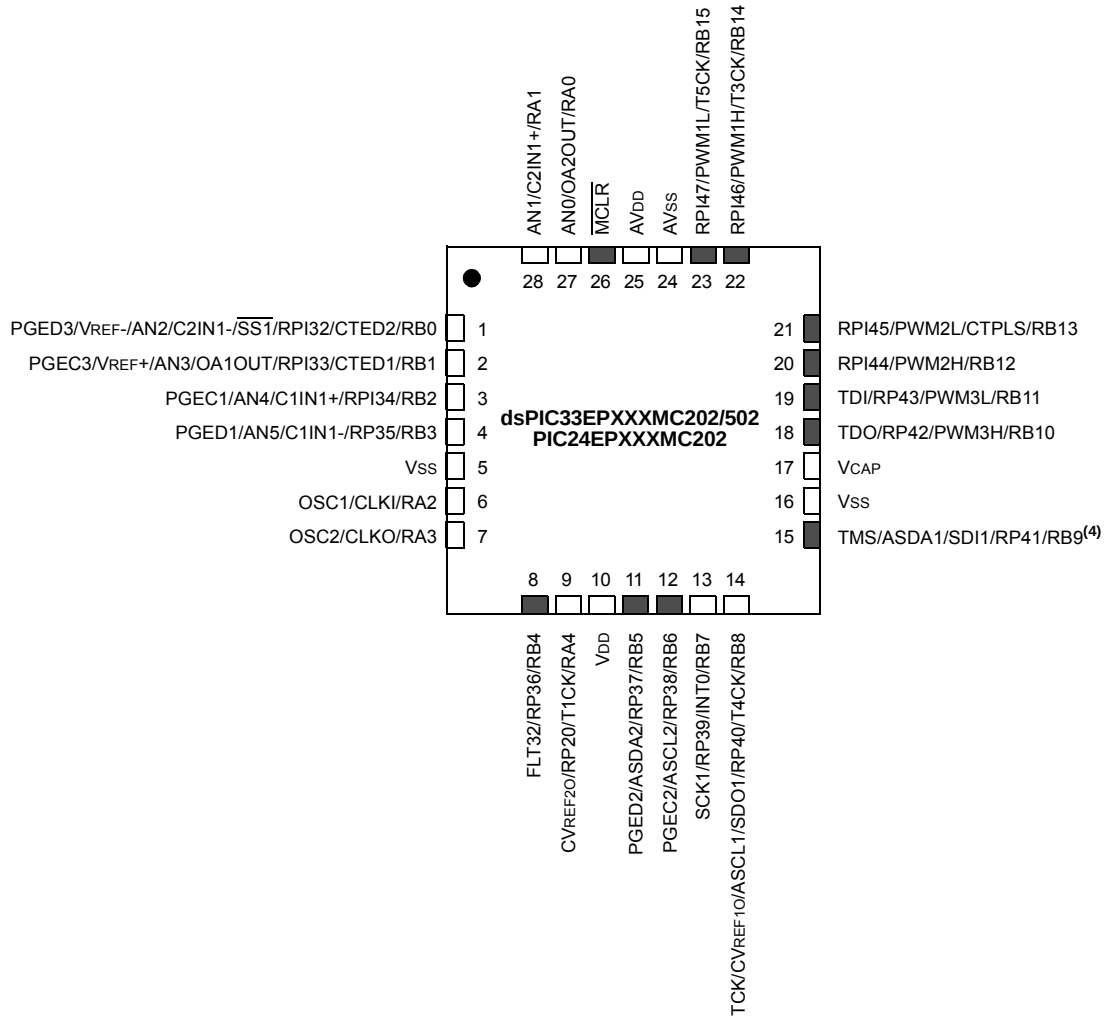
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep128gp506t-e-mr

Pin Diagrams (Continued)

28-Pin QFN-S(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

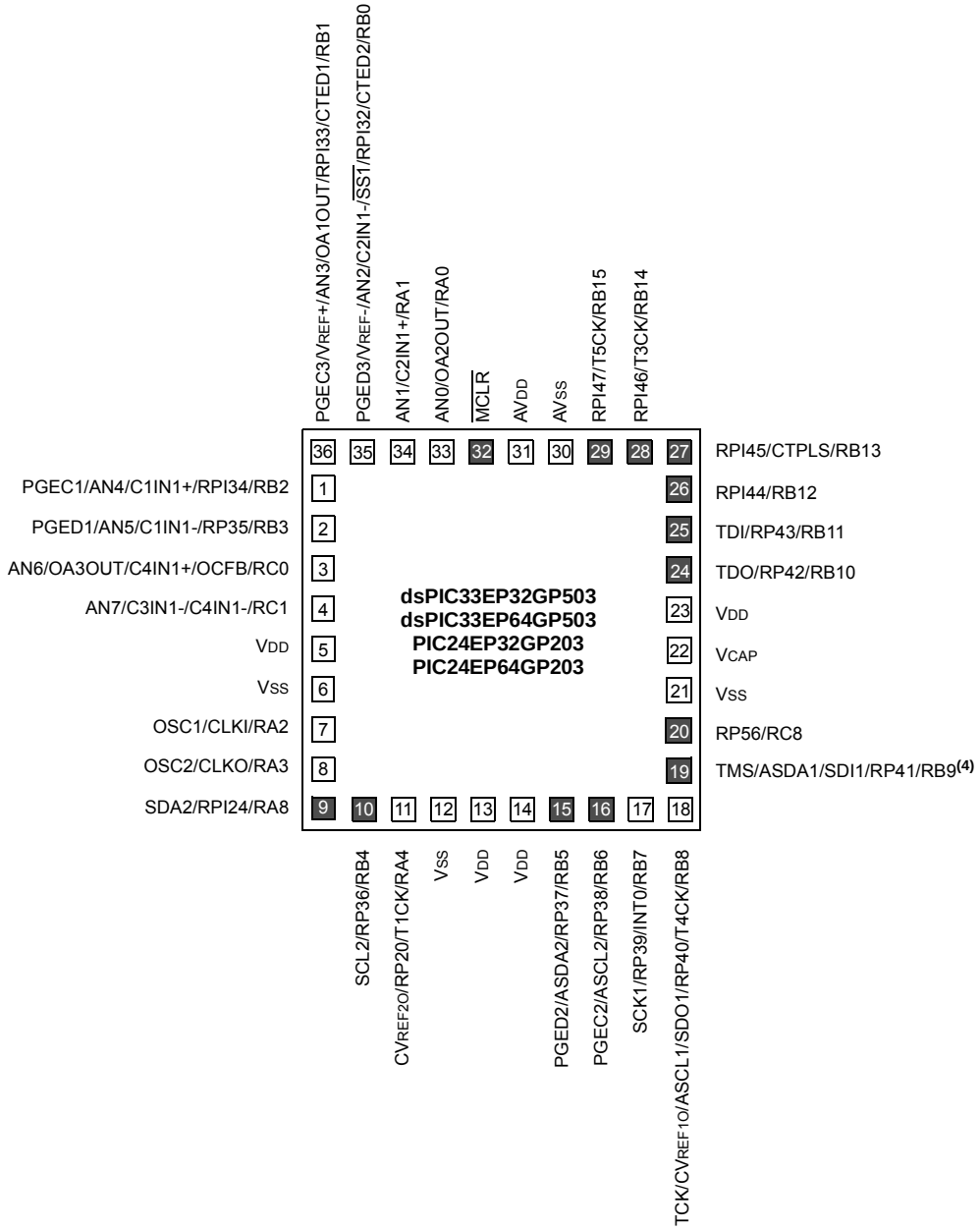
3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

Pin Diagrams (Continued)

36-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

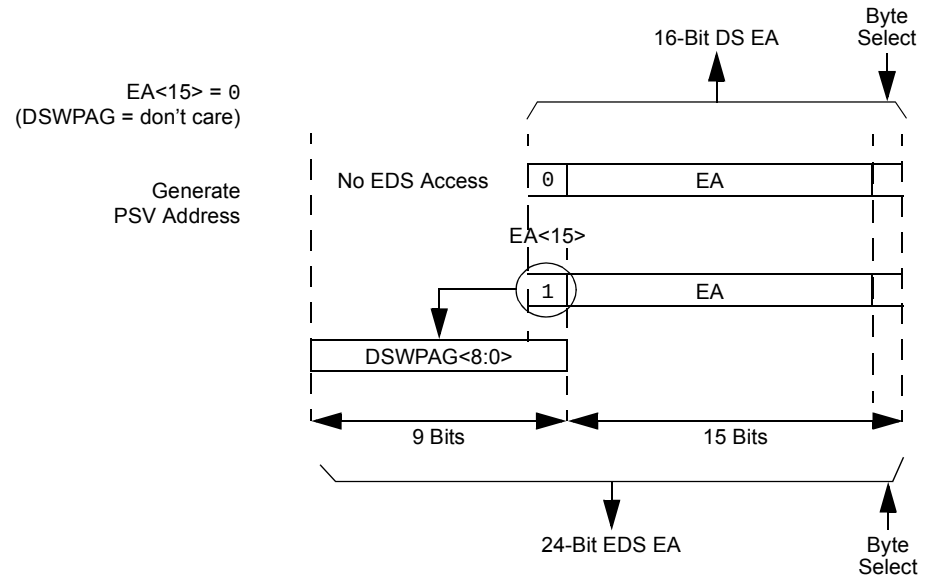
4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

TABLE 4-2: CPU CORE REGISTER MAP FOR PIC24EPXXXGP/MC20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
W0	0000	W0 (WREG)																xxxx
W1	0002	W1																xxxx
W2	0004	W2																xxxx
W3	0006	W3																xxxx
W4	0008	W4																xxxx
W5	000A	W5																xxxx
W6	000C	W6																xxxx
W7	000E	W7																xxxx
W8	0010	W8																xxxx
W9	0012	W9																xxxx
W10	0014	W10																xxxx
W11	0016	W11																xxxx
W12	0018	W12																xxxx
W13	001A	W13																xxxx
W14	001C	W14																xxxx
W15	001E	W15																xxxx
SPLIM	0020	SPLIM<15:0>																0000
PCL	002E	PCL<15:1>															—	0000
PCH	0030	—	—	—	—	—	—	—	—	—	PCH<6:0>							0000
DSRPAG	0032	—	—	—	—	—	—	DSRPAG<9:0>										0001
DSWPAG	0034	—	—	—	—	—	—	—	DSWPAG<8:0>									0001
RCOUNT	0036	RCOUNT<15:0>																0000
SR	0042	—	—	—	—	—	—	—	DC	IPL2	IPL1	IPL0	RA	N	OV	Z	C	0000
CORCON	0044	VAR	—	—	—	—	—	—	—	—	—	—	—	IPL3	SFA	—	—	0020
DISICNT	0052	—	—	DISICNT<13:0>														0000
TBLPAG	0054	—	—	—	—	—	—	—	—	TBLPAG<7:0>								0000
MSTRPR	0058	MSTRPR<15:0>																0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

EXAMPLE 4-2: EXTENDED DATA SPACE (EDS) WRITE ADDRESS GENERATION



Note: DS read access when DSRPAG = 0x000 will force an address error trap.

The paged memory scheme provides access to multiple 32-Kbyte windows in the EDS and PSV memory. The Data Space Page registers, DSxPAG, in combination with the upper half of the Data Space address, can provide up to 16 Mbytes of additional address space in the EDS and 8 Mbytes (DSRPAG only) of PSV address space. The paged data memory space is shown in Example 4-3.

The Program Space (PS) can be accessed with a DSRPAG of 0x200 or greater. Only reads from PS are supported using the DSRPAG. Writes to PS are not supported, so DSWPAG is dedicated to DS, including EDS only. The Data Space and EDS can be read from, and written to, using DSRPAG and DSWPAG, respectively.

TABLE 7-1: INTERRUPT VECTOR DETAILS (CONTINUED)

Interrupt Source	Vector #	IRQ #	IVT Address	Interrupt Bit Location		
				Flag	Enable	Priority
QEI1 – QEI1 Position Counter Compare(2)	66	58	0x000088	IFS3<10>	IEC3<10>	IPC14<10:8>
Reserved	67-72	59-64	0x00008A-0x000094	—	—	—
U1E – UART1 Error Interrupt	73	65	0x000096	IFS4<1>	IEC4<1>	IPC16<6:4>
U2E – UART2 Error Interrupt	74	66	0x000098	IFS4<2>	IEC4<2>	IPC16<10:8>
CRC – CRC Generator Interrupt	75	67	0x00009A	IFS4<3>	IEC4<3>	IPC16<14:12>
Reserved	76-77	68-69	0x00009C-0x00009E	—	—	—
C1TX – CAN1 TX Data Request(1)	78	70	0x000A0	IFS4<6>	IEC4<6>	IPC17<10:8>
Reserved	79-84	71-76	0x0000A2-0x0000AC	—	—	—
CTMU – CTMU Interrupt	85	77	0x0000AE	IFS4<13>	IEC4<13>	IPC19<6:4>
Reserved	86-101	78-93	0x0000B0-0x0000CE	—	—	—
PWM1 – PWM Generator 1(2)	102	94	0x0000D0	IFS5<14>	IEC5<14>	IPC23<10:8>
PWM2 – PWM Generator 2(2)	103	95	0x0000D2	IFS5<15>	IEC5<15>	IPC23<14:12>
PWM3 – PWM Generator 3(2)	104	96	0x0000D4	IFS6<0>	IEC6<0>	IPC24<2:0>
Reserved	105-149	97-141	0x0001D6-0x00012E	—	—	—
ICD – ICD Application	150	142	0x000142	IFS8<14>	IEC8<14>	IPC35<10:8>
JTAG – JTAG Programming	151	143	0x000130	IFS8<15>	IEC8<15>	IPC35<14:12>
Reserved	152	144	0x000134	—	—	—
PTGSTEP – PTG Step	153	145	0x000136	IFS9<1>	IEC9<1>	IPC36<6:4>
PTGWDT – PTG Watchdog Time-out	154	146	0x000138	IFS9<2>	IEC9<2>	IPC36<10:8>
PTG0 – PTG Interrupt 0	155	147	0x00013A	IFS9<3>	IEC9<3>	IPC36<14:12>
PTG1 – PTG Interrupt 1	156	148	0x00013C	IFS9<4>	IEC9<4>	IPC37<2:0>
PTG2 – PTG Interrupt 2	157	149	0x00013E	IFS9<5>	IEC9<5>	IPC37<6:4>
PTG3 – PTG Interrupt 3	158	150	0x000140	IFS9<6>	IEC9<6>	IPC37<10:8>
Reserved	159-245	151-245	0x000142-0x0001FE	—	—	—
Lowest Natural Order Priority						

Note 1: This interrupt source is available on dsPIC33EPXXXGP50X and dsPIC33EPXXXMC50X devices only.

2: This interrupt source is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

9.0 OSCILLATOR CONFIGURATION

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Oscillator"** (DS70580) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

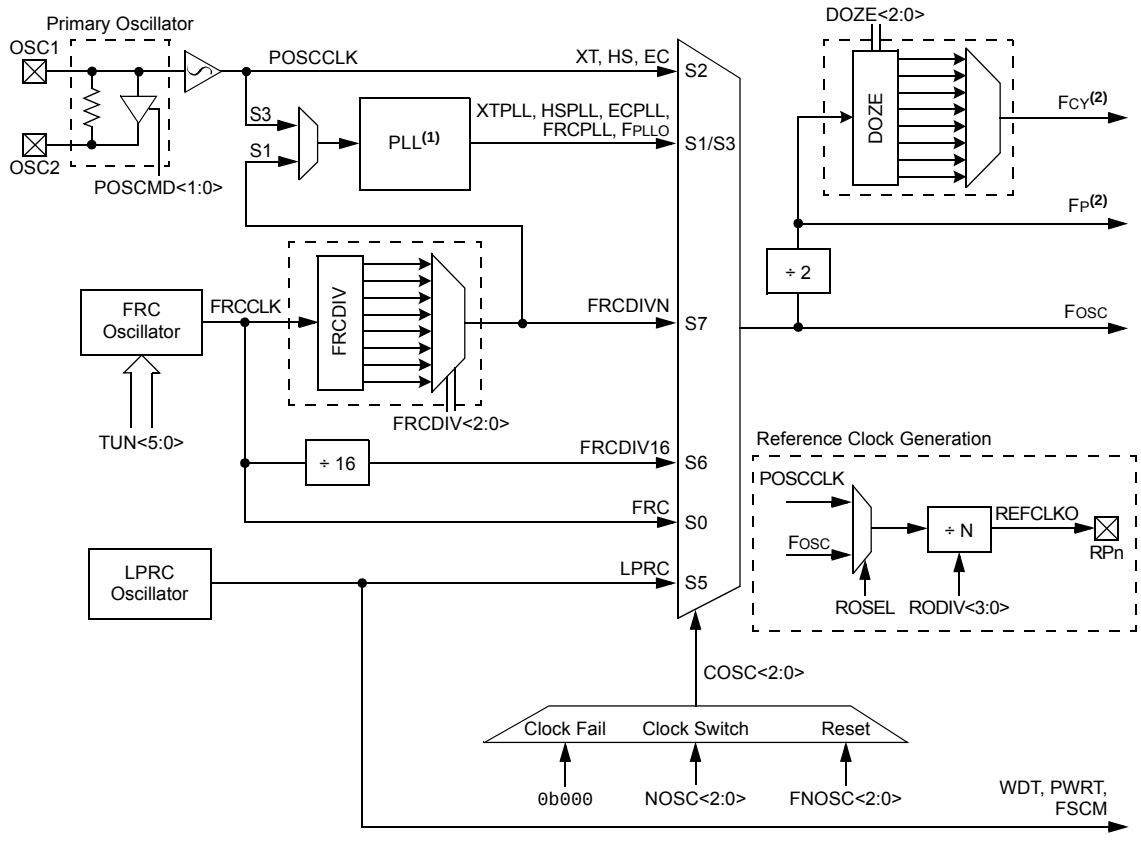
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X oscillator system provides:

- On-chip Phase-Locked Loop (PLL) to boost internal operating frequency on select internal and external oscillator sources
- On-the-fly clock switching between various clock sources
- Doze mode for system power savings
- Fail-Safe Clock Monitor (FSCM) that detects clock failure and permits safe application recovery or shutdown
- Configuration bits for clock source selection

A simplified diagram of the oscillator system is shown in Figure 9-1.

FIGURE 9-1: OSCILLATOR SYSTEM DIAGRAM



Note 1: See Figure 9-2 for PLL details.

2: The term, FP, refers to the clock source for all peripherals, while FCY refers to the clock source for the CPU. Throughout this document, FCY and FP are used interchangeably, except in the case of Doze mode. FP and FCY will be different when Doze mode is used with a doze ratio of 1:2 or lower.

10.2.1 SLEEP MODE

The following occurs in Sleep mode:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption is reduced to a minimum, provided that no I/O pin is sourcing current.
- The Fail-Safe Clock Monitor does not operate, since the system clock source is disabled.
- The LPRC clock continues to run in Sleep mode if the WDT is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals can continue to operate. This includes items such as the Input Change Notification (ICN) on the I/O ports or peripherals that use an external clock input.
- Any peripheral that requires the system clock source for its operation is disabled.

The device wakes up from Sleep mode on any of these events:

- Any interrupt source that is individually enabled
- Any form of device Reset
- A WDT time-out

On wake-up from Sleep mode, the processor restarts with the same clock source that was active when Sleep mode was entered.

For optimal power savings, the internal regulator and the Flash regulator can be configured to go into Standby when Sleep mode is entered by clearing the VREGS (RCON<8>) and VREGSF (RCON<11>) bits (default configuration).

If the application requires a faster wake-up time, and can accept higher current requirements, the VREGS (RCON<8>) and VREGSF (RCON<11>) bits can be set to keep the internal regulator and the Flash regulator active during Sleep mode.

10.2.2 IDLE MODE

The following occurs in Idle mode:

- The CPU stops executing instructions.
- The WDT is automatically cleared.
- The system clock source remains active. By default, all peripheral modules continue to operate normally from the system clock source, but can also be selectively disabled (see **Section 10.4 “Peripheral Module Disable”**).
- If the WDT or FSCM is enabled, the LPRC also remains active.

The device wakes from Idle mode on any of these events:

- Any interrupt that is individually enabled
- Any device Reset
- A WDT time-out

On wake-up from Idle mode, the clock is reapplied to the CPU and instruction execution will begin (2-4 clock cycles later), starting with the instruction following the PWRSAV instruction or the first instruction in the Interrupt Service Routine (ISR).

All peripherals also have the option to discontinue operation when Idle mode is entered to allow for increased power savings. This option is selectable in the control register of each peripheral; for example, the TSIDL bit in the Timer1 Control register (T1CON<13>).

10.2.3 INTERRUPTS COINCIDENT WITH POWER SAVE INSTRUCTIONS

Any interrupt that coincides with the execution of a PWRSAV instruction is held off until entry into Sleep or Idle mode has completed. The device then wakes up from Sleep or Idle mode.

REGISTER 10-5: PMD6: PERIPHERAL MODULE DISABLE CONTROL REGISTER 6

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	PWM3MD(1)	PWM2MD(1)	PWM1MD(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10 **PWM3MD:** PWM3 Module Disable bit(1)
1 = PWM3 module is disabled
0 = PWM3 module is enabled

bit 9 **PWM2MD:** PWM2 Module Disable bit(1)
1 = PWM2 module is disabled
0 = PWM2 module is enabled

bit 8 **PWM1MD:** PWM1 Module Disable bit(1)
1 = PWM1 module is disabled
0 = PWM1 module is enabled

bit 7-0 **Unimplemented:** Read as '0'

Note 1: This bit is available on dsPIC33EPXXXMC50X/20X and PIC24EPXXXMC20X devices only.

REGISTER 11-17: RPINR39: PERIPHERAL PIN SELECT INPUT REGISTER 39 (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	DTCMP3R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	DTCMP2R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **DTCMP3R<6:0>:** Assign PWM Dead-Time Compensation Input 3 to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **DTCMP2R<6:0>:** Assign PWM Dead-Time Compensation Input 2 to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

REGISTER 16-17: LEBDLYx: PWMx LEADING-EDGE BLANKING DELAY REGISTER

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	LEB<11:8>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
LEB<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11-0 **LEB<11:0>:** Leading-Edge Blanking Delay for Current-Limit and Fault Inputs bits

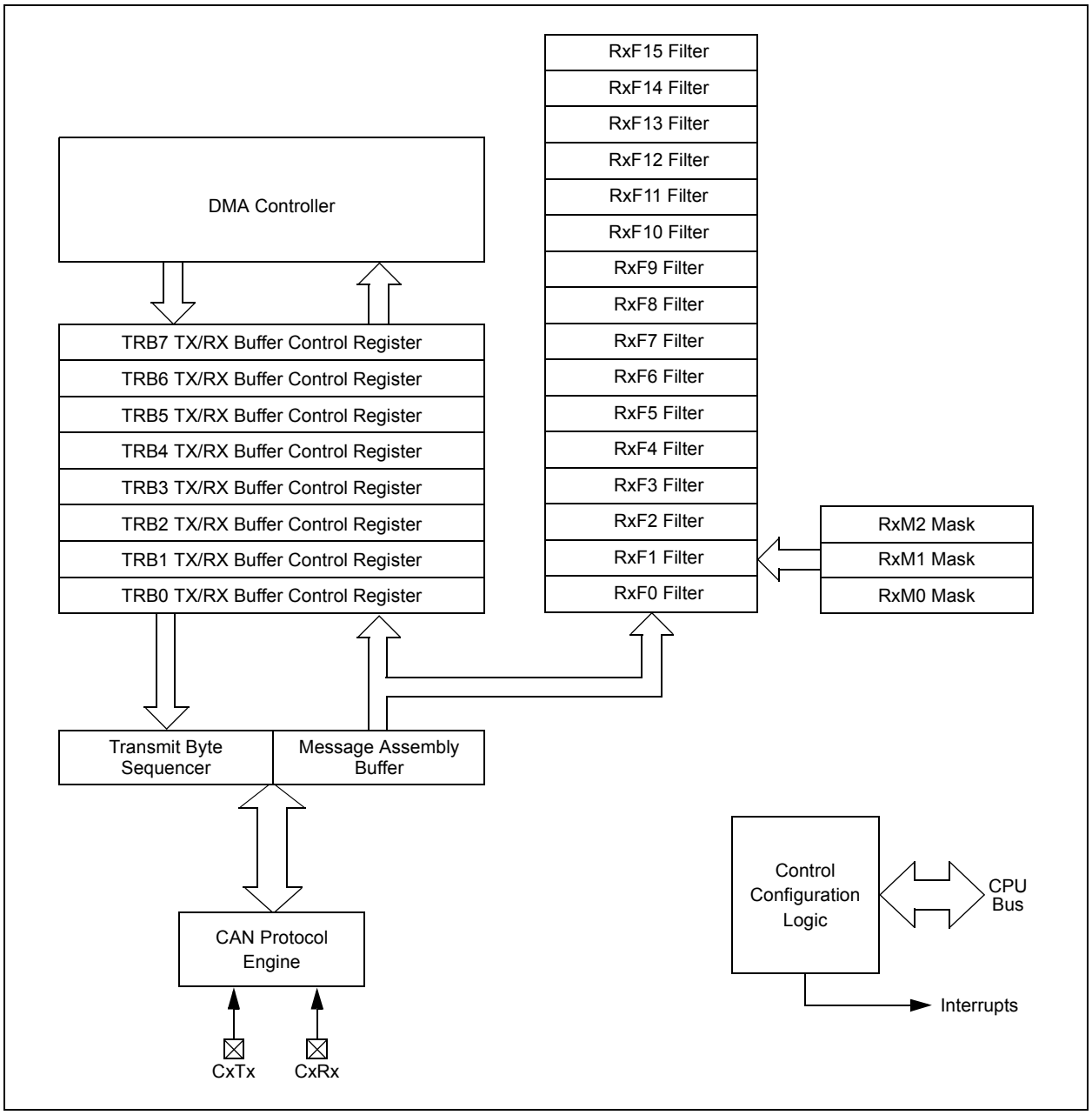
REGISTER 18-2: SPIxCON1: SPIx CONTROL REGISTER 1 (CONTINUED)

bit 4-2 **SPRE<2:0>:** Secondary Prescale bits (Master mode)(3)
111 = Secondary prescale 1:1
110 = Secondary prescale 2:1
•
•
•
000 = Secondary prescale 8:1

bit 1-0 **PPRE<1:0>:** Primary Prescale bits (Master mode)(3)
11 = Primary prescale 1:1
10 = Primary prescale 4:1
01 = Primary prescale 16:1
00 = Primary prescale 64:1

Note 1: The CKE bit is not used in Framed SPI modes. Program this bit to '0' for Framed SPI modes (FRMEN = 1).
2: This bit must be cleared when FRMEN = 1.
3: Do not set both primary and secondary prescalers to the value of 1:1.

FIGURE 21-1: ECAN™ MODULE BLOCK DIAGRAM



REGISTER 21-10: CxCFG2: ECANx BAUD RATE CONFIGURATION REGISTER 2

U-0	R/W-x	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	WAKFIL	—	—	—	SEG2PH2	SEG2PH1	SEG2PH0
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SEG2PHTS	SAM	SEG1PH2	SEG1PH1	SEG1PH0	PRSEG2	PRSEG1	PRSEG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14 **WAKFIL:** Select CAN Bus Line Filter for Wake-up bit
1 = Uses CAN bus line filter for wake-up
0 = CAN bus line filter is not used for wake-up

bit 13-11 **Unimplemented:** Read as '0'

bit 10-8 **SEG2PH<2:0>:** Phase Segment 2 bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

bit 7 **SEG2PHTS:** Phase Segment 2 Time Select bit
1 = Freely programmable
0 = Maximum of SEG1PHx bits or Information Processing Time (IPT), whichever is greater

bit 6 **SAM:** Sample of the CAN Bus Line bit
1 = Bus line is sampled three times at the sample point
0 = Bus line is sampled once at the sample point

bit 5-3 **SEG1PH<2:0>:** Phase Segment 1 bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

bit 2-0 **PRSEG<2:0>:** Propagation Time Segment bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

REGISTER 23-1: AD1CON1: ADC1 CONTROL REGISTER 1 (CONTINUED)

bit 7-5 **SSRC<2:0>:** Sample Trigger Source Select bits

If SSRCG = 1:

111 = Reserved
110 = PTGO15 primary trigger compare ends sampling and starts conversion(1)
101 = PTGO14 primary trigger compare ends sampling and starts conversion(1)
100 = PTGO13 primary trigger compare ends sampling and starts conversion(1)
011 = PTGO12 primary trigger compare ends sampling and starts conversion(1)
010 = PWM Generator 3 primary trigger compare ends sampling and starts conversion(2)
001 = PWM Generator 2 primary trigger compare ends sampling and starts conversion(2)
000 = PWM Generator 1 primary trigger compare ends sampling and starts conversion(2)

If SSRCG = 0:

111 = Internal counter ends sampling and starts conversion (auto-convert)
110 = CTMU ends sampling and starts conversion
101 = Reserved
100 = Timer5 compare ends sampling and starts conversion
011 = PWM primary Special Event Trigger ends sampling and starts conversion(2)
010 = Timer3 compare ends sampling and starts conversion
001 = Active transition on the INT0 pin ends sampling and starts conversion
000 = Clearing the Sample bit (SAMP) ends sampling and starts conversion (Manual mode)

bit 4 **SSRCG:** Sample Trigger Source Group bit

See SSRC<2:0> for details.

bit 3 **SIMSAM:** Simultaneous Sample Select bit (only applicable when CHPS<1:0> = 01 or 1x)

In 12-bit mode (AD21B = 1), SIMSAM is Unimplemented and is Read as '0':

1 = Samples CH0, CH1, CH2, CH3 simultaneously (when CHPS<1:0> = 1x); or samples CH0 and CH1 simultaneously (when CHPS<1:0> = 01)
0 = Samples multiple channels individually in sequence

bit 2 **ASAM:** ADC1 Sample Auto-Start bit

1 = Sampling begins immediately after the last conversion; SAMP bit is auto-set
0 = Sampling begins when the SAMP bit is set

bit 1 **SAMP:** ADC1 Sample Enable bit

1 = ADC Sample-and-Hold amplifiers are sampling
0 = ADC Sample-and-Hold amplifiers are holding

If ASAM = 0, software can write '1' to begin sampling. Automatically set by hardware if ASAM = 1. If SSRC<2:0> = 000, software can write '0' to end sampling and start conversion. If SSRC<2:0> ≠ 000, automatically cleared by hardware to end sampling and start conversion.

bit 0 **DONE:** ADC1 Conversion Status bit(3)

1 = ADC conversion cycle has completed
0 = ADC conversion has not started or is in progress

Automatically set by hardware when the ADC conversion is complete. Software can write '0' to clear the DONE status bit (software is not allowed to write '1'). Clearing this bit does NOT affect any operation in progress. Automatically cleared by hardware at the start of a new conversion.

Note 1: See **Section 24.0 "Peripheral Trigger Generator (PTG) Module"** for information on this selection.
2: This setting is available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
3: Do not clear the DONE bit in software if Auto-Sample is enabled (ASAM = 1).

REGISTER 25-5: CMxMSKCON: COMPARATOR x MASK GATING CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OANEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **HLMS:** High or Low-Level Masking Select bits
1 = The masking (blanking) function will prevent any asserted ('0') comparator signal from propagating
0 = The masking (blanking) function will prevent any asserted ('1') comparator signal from propagating

bit 14 **Unimplemented:** Read as '0'

bit 13 **OCEN:** OR Gate C Input Enable bit
1 = MCI is connected to OR gate
0 = MCI is not connected to OR gate

bit 12 **OCNEN:** OR Gate C Input Inverted Enable bit
1 = Inverted MCI is connected to OR gate
0 = Inverted MCI is not connected to OR gate

bit 11 **OBEN:** OR Gate B Input Enable bit
1 = MBI is connected to OR gate
0 = MBI is not connected to OR gate

bit 10 **OBNEN:** OR Gate B Input Inverted Enable bit
1 = Inverted MBI is connected to OR gate
0 = Inverted MBI is not connected to OR gate

bit 9 **OAEN:** OR Gate A Input Enable bit
1 = MAI is connected to OR gate
0 = MAI is not connected to OR gate

bit 8 **OANEN:** OR Gate A Input Inverted Enable bit
1 = Inverted MAI is connected to OR gate
0 = Inverted MAI is not connected to OR gate

bit 7 **NAGS:** AND Gate Output Inverted Enable bit
1 = Inverted ANDI is connected to OR gate
0 = Inverted ANDI is not connected to OR gate

bit 6 **PAGS:** AND Gate Output Enable bit
1 = ANDI is connected to OR gate
0 = ANDI is not connected to OR gate

bit 5 **ACEN:** AND Gate C Input Enable bit
1 = MCI is connected to AND gate
0 = MCI is not connected to AND gate

bit 4 **ACNEN:** AND Gate C Input Inverted Enable bit
1 = Inverted MCI is connected to AND gate
0 = Inverted MCI is not connected to AND gate

TABLE 30-40: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-48: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 91 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-53: OP AMP/COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
Comparator AC Characteristics							
CM10	TRESP	Response Time(3)	—	19	—	ns	V+ input step of 100 mV, V- input held at VDD/2
CM11	TMC2OV	Comparator Mode Change to Output Valid	—	—	10	µs	
Comparator DC Characteristics							
CM30	VOFFSET	Comparator Offset Voltage	—	±10	40	mV	
CM31	VHYST	Input Hysteresis Voltage(3)	—	30	—	mV	
CM32	TRISE/ TFALL	Comparator Output Rise/ Fall Time(3)	—	20	—	ns	1 pF load capacitance on input
CM33	VGAIN	Open-Loop Voltage Gain(3)	—	90	—	db	
CM34	VICM	Input Common-Mode Voltage	AVSS	—	AVDD	V	
Op Amp AC Characteristics							
CM20	SR	Slew Rate(3)	—	9	—	V/µs	10 pF load
CM21a	PM	Phase Margin (Configuration A)(3,4)	—	55	—	Degree	G = 100V/V; 10 pF load
CM21b	PM	Phase Margin (Configuration B)(3,5)	—	40	—	Degree	G = 100V/V; 10 pF load
CM22	GM	Gain Margin(3)	—	20	—	db	G = 100V/V; 10 pF load
CM23a	GBW	Gain Bandwidth (Configuration A)(3,4)	—	10	—	MHz	10 pF load
CM23b	GBW	Gain Bandwidth (Configuration B)(3,5)	—	6	—	MHz	10 pF load

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: Parameter is characterized but not tested in manufacturing.

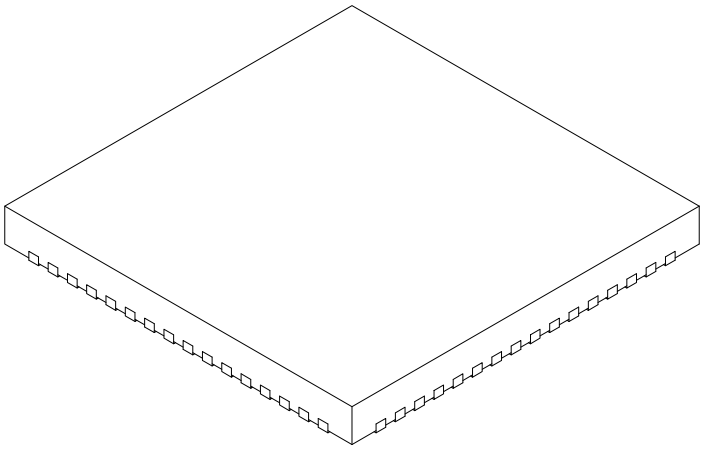
4: See Figure 25-6 for configuration information.

5: See Figure 25-7 for configuration information.

6: Resistances can vary by ±10% between op amps.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body with 5.40 x 5.40 Exposed Pad [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		64	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		9.00 BSC	
Exposed Pad Width	E2	5.30	5.40	5.50
Overall Length	D		9.00 BSC	
Exposed Pad Length	D2	5.30	5.40	5.50
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-154A Sheet 2 of 2